3.0mmx1.0 mm RIGHT ANGLE SMD CHIP LED LAMP

Part Number: APA3010SGC-GX

Super Bright Green

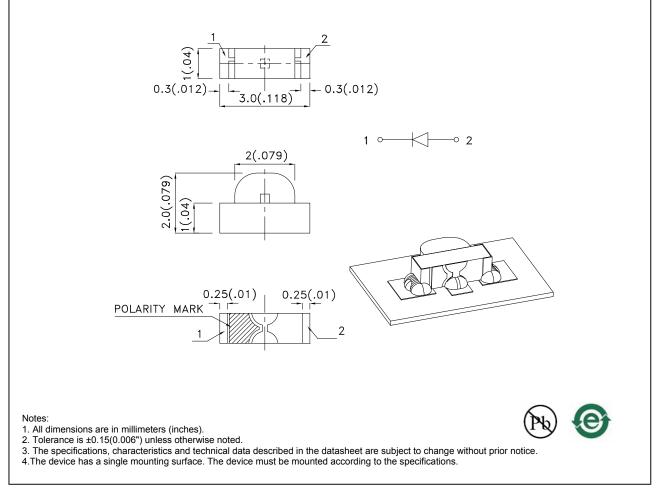
Features

- 3.0mmx1.0mm right angle SMT LED, 2.0mm thickness.
- Low power consumption.
- Wide viewing angle.
- Ideal for back light and indicator.
- Various colors and lens types available.
- Package : 2000pcs / reel.
- Moisture sensitivity level : level 3.
- Tinned pads for improved solderability.
- RoHS compliant.

Description

The Super Bright Green source color devices are made with Gallium Phosphide Green Light Emitting Diode.

Package Dimensions



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Selection Guide									
Part No.	Dice	Lens Type	Min.	Тур.	201/2				
APA3010SGC-GX	Super Bright Green (GaP)	Water Clear	8	15	120°				

Notes: 1. θ 1/2 is the angle from optical centerline where the luminous intensity is 1/2 of the optical peak value. 2. Luminous intensity/ luminous Flux: +/-15%.

Electrical / Optical Characteristics at TA=25°C

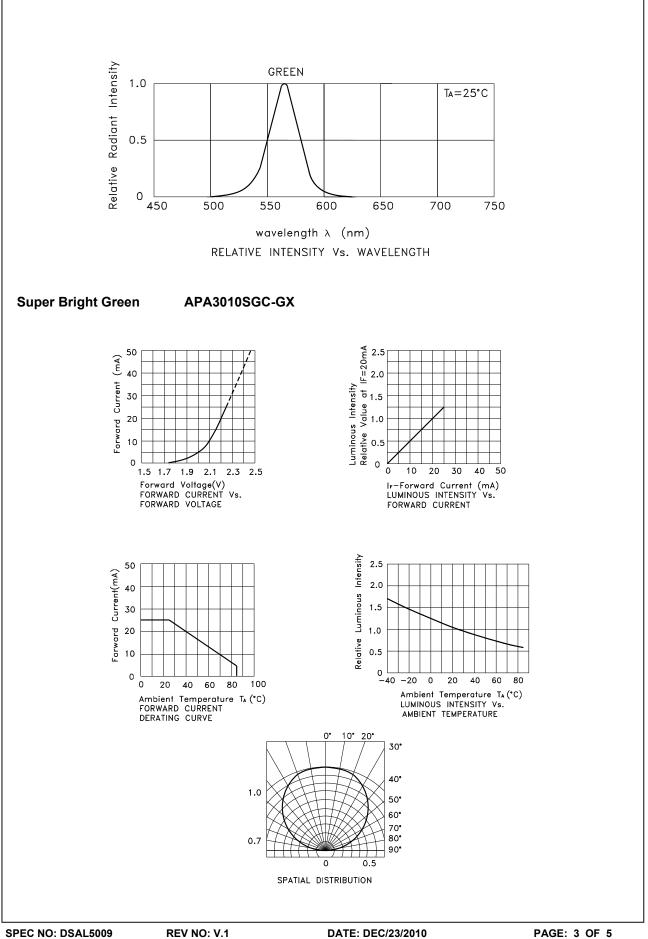
Symbol	Parameter	Device	Тур.	Max.	Units	Test Conditions
λpeak	Peak Wavelength	Super Bright Green	565		nm	I⊧=20mA
λD [1]	Dominant Wavelength	Super Bright Green	568		nm	I⊧=20mA
Δλ1/2	Spectral Line Half-width	Super Bright Green	30		nm	IF=20mA
С	Capacitance	Super Bright Green	15		pF	VF=0V;f=1MHz
VF [2]	Forward Voltage	Super Bright Green	2.2	2.5	V	I⊧=20mA
IR	Reverse Current	Super Bright Green		10	uA	VR=5V

Notes: 1.Wavelength: +/-1nm. 2. Forward Voltage: +/-0.1V.

Absolute Maximum Ratings at TA=25°C

Parameter	Super Bright Green	Units		
Power dissipation	62.5	mW		
DC Forward Current	25	mA		
Peak Forward Current [1]	140	mA		
Reverse Voltage	5	V		
Operating Temperature	-40°C To +85°C			
Storage Temperature	-40°C To +85°C			

Note: 1. 1/10 Duty Cycle, 0.1ms Pulse Width.



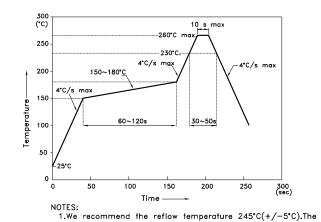
APA3010SGC-GX

Reflow soldering is recommended and the soldering profile is shown below. Other soldering methods are not recommended as they might cause damage to the product.

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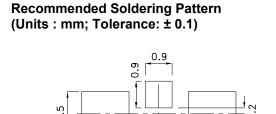
1.5

Reflow Soldering Profile For Lead-free SMT Process.



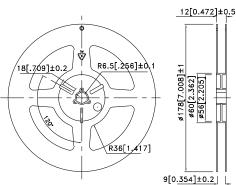
NOTES: 1.We recommend the reflow temperature 245°C(+/-5°C).The maximum soldering temperature should be limited to 260°C. 2.Don't cause stress to the epoxy resin while it is exposed to high temperature.

to high temperature. 3.Number of reflow process shall be 2 times or less.



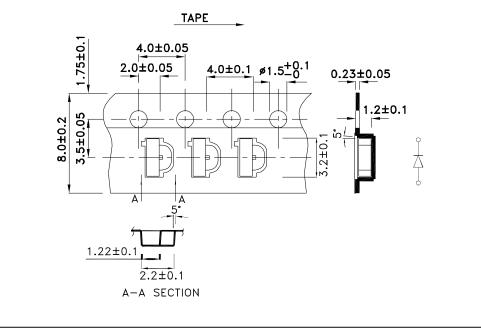
5.0

Reel Dimension



Tape Dimensions (Units : mm)

1.5



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